

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 03-135011

(43)Date of publication of application : 10.06.1991

(51)Int. CI.

H01L 21/027

B05D 3/02

(21)Application number : 01-273599

(71)Applicant : TOKYO ELECTRON LTD
TOKYO EREKUTORON KYUSHU
KK

(22)Date of filing : 20.10.1989

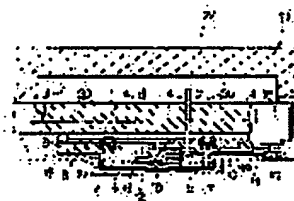
(72)Inventor : HIRAKAWA OSAMU
FUJIMOTO AKIHIRO
TERAOKA SEIICHI

(54) HEATING TREATMENT FOR SUBSTRATE

(57)Abstract:

PURPOSE: To make an apparatus small-sized by a method wherein, when a substrate to be treated is heat-treated by using heat of a heating plate at a second temperature after a heat treatment at a first temperature, an interval between the heating plate and the substrate to be treated is changed and the substrate is set to the second treatment temperature.

CONSTITUTION: A heating plate 2 is set in advance to a prescribed temperature; in a stage that pins 4 protrude on the heating plate 2, a semiconductor wafer 3 is placed on the pins 4. Then, the pins 4 are lowered; the wafer 3 is placed on proximity pins 20. A heating operation is executed for a prescribed time; a stepping motor 15 is driven; the pins 4 are raised; the wafer 3 is delivered from the pins 20 to the pins 4; a proximity gap is set to a prescribed value; a heating operation is executed for a prescribed time. When a treatment temperature is to be changed further, the pins 4 are moved up and down, and the proximity gap is changed and adjusted. Thereby, the treatment temperature of the semiconductor wafer 2 can be set to a desired temperature without changing a temperature of a heating plate 1.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision
of rejection]

[Kind of final disposal of application
other than the examiner's decision of
rejection or application converted
registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's
decision of rejection]

[Date of requesting appeal against
examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998, 2003 Japan Patent Office